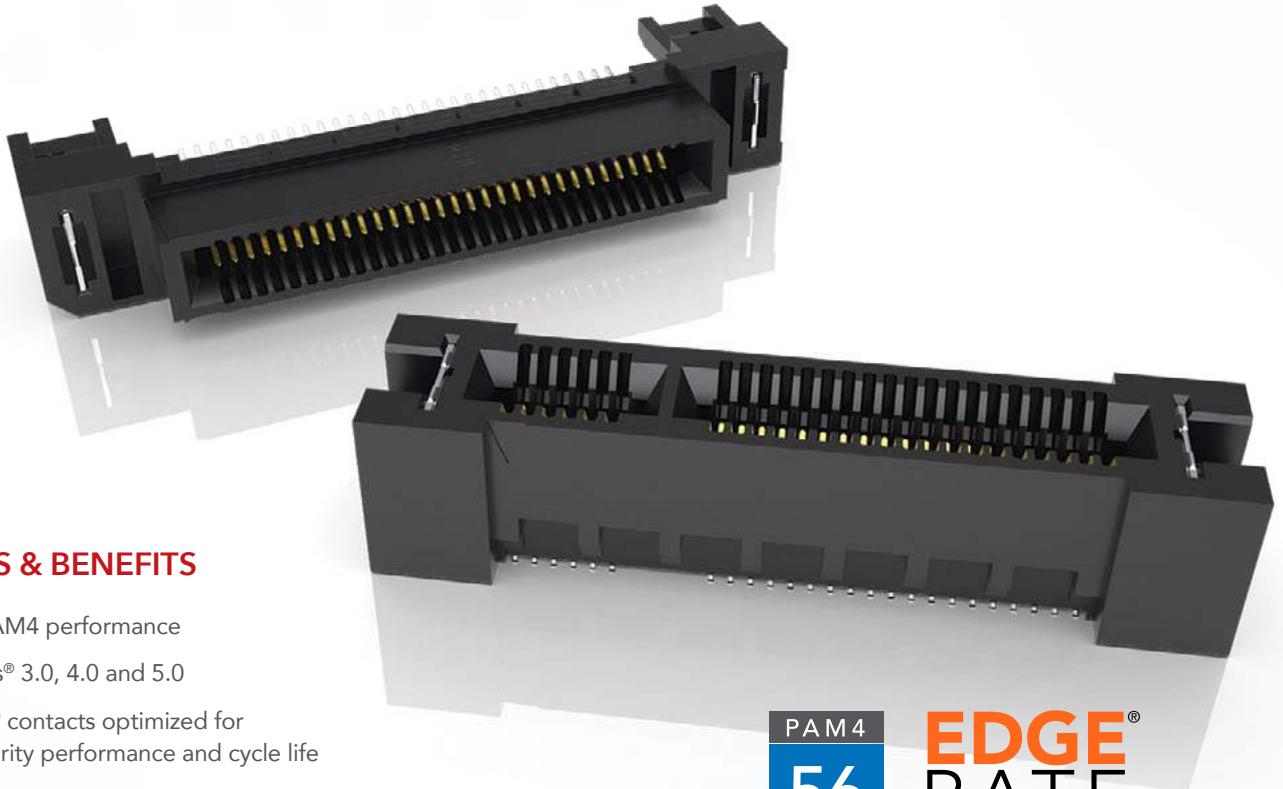


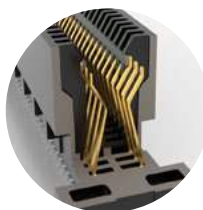
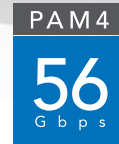
HIGH-SPEED EDGE CARD SYSTEMS

0.60 mm, 0.80 mm and 1.00 mm PITCH



FEATURES & BENEFITS

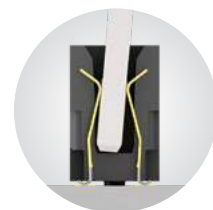
- 56 Gbps PAM4 performance
- PCI Express® 3.0, 4.0 and 5.0
- Edge Rate® contacts optimized for signal integrity performance and cycle life
- Up to 200 positions available
- Vertical, right-angle, edge mount, pass-through orientations
- Power/signal combo, press-fit tails, rugged weld tabs, locks and latches
- Mating cable assemblies available



Rugged tucked beam technology (HTEC8)



Differential pair for increased speed (HSEC8-DP)



Custom designs allow for misalignment in the X-Y axes (HSEC1)

KEY SPECIFICATIONS

SERIES	PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
HSEC6	0.60 mm	56-168	Black LCP	Copper Alloy	-55 °C to +125 °C	0.8 A (12 pins)	300 VAC	Yes
HTEC8	0.80 mm	40-200	Black LCP	Copper Alloy	-55 °C to +125 °C	3.0 A (2 pins)	215 VAC	Yes
HSEC8	0.80 mm	18-200	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC	Yes
HSEC1	1.00 mm	20-140	Black LCP	Phosphor Bronze	-55 °C to +125 °C	2.2 A (2 pins)	215 VAC	Yes

(0.80 mm) .0315" PITCH • RIGHT-ANGLE & EDGE MOUNT SOCKET

HSEC8	1	POSITIONS PER ROW	CARD THICKNESS	PLATING OPTION	RA	OTHER OPTIONS	"X"R
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09, 10, 13, 20,
25, 30, 40, 49,
50, 60

-01
= (1.60 mm) .062"
thick card

-L
= 10 μ" (0.25 μm)
Gold on contact area,
Matte Tin on tail

-S
= 30 μ" (0.76 μm)
Gold on contact area,
Matte Tin on tail

-BL
= Board Locks (09, 13,
25, 40, 49, 50, 60 only)

-L2
= ECDP Latching
(09, 13, 25, 49 only)

Leave blank for
Tray Packaging

-TR
= Tape & Reel

-FR
= Full Reel
Tape & Reel Packaging
(must order max.
quantity per reel;
contact Samtec for
quantity breaks)

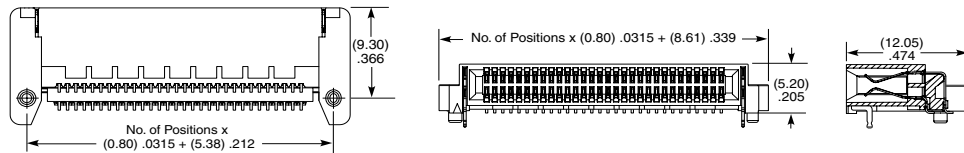
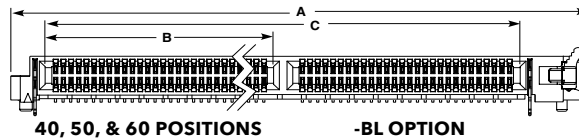
HSEC8-RA

Card Mates:
(1.60 mm) .062"
thick card,
HSC8

Cable Mates:
ECDP



POSITIONS PER ROW	A	B	C
40	(43.80) 1.724	(18.90) .744	(36.60) 1.441
50	(51.80) 2.039	(22.90) .902	(44.60) 1.756
60	(59.80) 2.354	(26.90) 1.059	(52.60) 2.071
40-BL	(51.30) 2.020	(18.90) .744	(36.60) 1.441
50-BL	(59.30) 2.335	(22.90) .902	(44.60) 1.756
60-BL	(67.30) 2.650	(26.90) 1.059	(52.60) 2.071



View complete specifications at: samtec.com?HSEC8-RA

HSEC8	1	POSITIONS PER ROW	01	PLATING OPTION	D	EM2
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10, 20, 30, 40,
50, 60

-L
= 10 μ" (0.25 μm)
Gold on contact area,
Matte Tin on tail

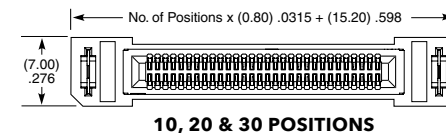
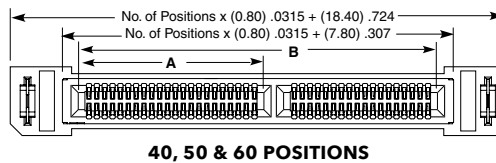
-S
= 30 μ" (0.76 μm)
Gold on contact area,
Matte Tin on tail

-EM2
=(1.60 mm) .062"
thick PCB

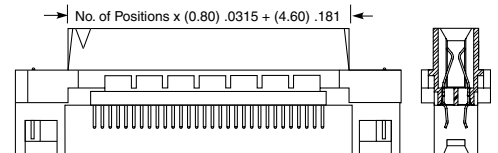
HSEC8-EM

Card Mates:
(1.60 mm) .062"
thick card,
HSC8

Cable Mates:
ECDP



POSITIONS PER ROW	A	B
40	(18.90) .744	(36.60) 1.441
50	(22.90) .902	(44.60) 1.756
60	(26.90) 1.059	(52.60) 2.071



Note:
Some sizes, styles and
options are non-standard,
non-returnable.

View complete specifications at: samtec.com?HSEC8-EM